

SSN08x summary material content, BI Technologies Corporation

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Highlighted line item is banned per E.U. RoHS. Prepared by Eric Arnold (714) 447-2565 or ericarnold@bitechnologies.com

Average mass of SSN08x Thin Film network is 0.08 grams each. Scientific notation is used for component masses.

Masses below 1E-5 grams are given as "trace"

Material name	also known as	CAS #	Mass per device (grams)	Special classification
Ag	silver	7440-22-4	1.28E-03	
Au	gold	7440-57-5	7.41E-05	
BCB	dvs-BCB, divinylsiloxane-bis-benzocyclobutene	124221-30-3	trace	
carbon black	lamp black, acetylene black	1333-86-4	2.08E-04	
Cu	copper	7440-50-8	2.78E-02	
epoxy curing agent		trade secret	1.36E-05	
epoxy resin		trade secret	1.23E-04	
epoxy resin, cresol novolac		29690-82-2	8.32E-04	
Fe	iron	7439-89-6	6.70E-04	
NiCrOx	nichrome	combination of 7440-02-0, 7440-47-3, & 1308-38-9	trace	
P	phosphorous, red or amorphous	7723-14-0	trace	
Pb	lead	7439-92-1	2.70E-04	E.U. RoHS banned material, SnPb plating on leads
Si	silicon	7440-21-3	2.55E-03	
SiO2, amorphous	silicon dioxide, silica	7631-86-9	trace	
SiO2, fused silica	silica glass	60676-86-0	3.64E-02	
Sn	tin	7440-31-5	1.08E-03	
WTi 10%	tungsten titanium 10%	combination of 7440-32-6 & 7440-33-7	trace	
trade secret		n/a	4.19E-03	Non-hazardous and not regulated
Zn	zinc	7440-66-6	3.42E-05	
		Sum of all components	0.08	